

BCR8PM-16LG

Triac

Medium Power Use

REJ03G1560-0100

Rev.1.00

Jul 06, 2007

Features

- $I_{T(RMS)}$: 8 A
- V_{DRM} : 800 V
- I_{FGTI} , I_{RGTI} , I_{RGTHI} : 30 mA
- V_{ISO} : 2000 V
- The Product guaranteed maximum junction temperature 150°C
- Insulated Type
- Planar Type
- UL Recognized: Yellow Card No. E223904
File No. E80271

Outline

RENESAS Package code: PRSS0003AA-A
(Package name: TO-220F)



1. T₁ Terminal
2. T₂ Terminal
3. Gate Terminal

Applications

Washing machine, inversion operation of capacitor motor, and other general controlling devices

Maximum Ratings

Parameter	Symbol	Voltage class	Unit
		16	
Repetitive peak off-state voltage ^{Note1}	V_{DRM}	800	V
Non-repetitive peak off-state voltage ^{Note1}	V_{DSM}	960	V

Parameter	Symbol	Ratings	Unit	Conditions
RMS on-state current	$I_T (RMS)$	8	A	Commercial frequency, sine full wave 360° conduction, $T_c = 107^\circ\text{C}$
Surge on-state current	I_{TSM}	80	A	60Hz sinewave 1 full cycle, peak value, non-repetitive
I^2t for fusing	I^2t	26	A^2s	Value corresponding to 1 cycle of half wave 60Hz, surge on-state current
Peak gate power dissipation	P_{GM}	5	W	
Average gate power dissipation	$P_{G(AV)}$	0.5	W	
Peak gate voltage	V_{GM}	10	V	
Peak gate current	I_{GM}	2	A	
Junction temperature	T_j	- 40 to +150	$^\circ\text{C}$	
Storage temperature	T_{stg}	- 40 to +150	$^\circ\text{C}$	
Mass	—	2.0	g	Typical value
Isolation voltage	Viso	2000	V	$T_a = 25^\circ\text{C}$, AC 1 minute, $T_1 \bullet T_2 \bullet G$ terminal to case

Notes: 1. Gate open.

Electrical Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions	
Repetitive peak off-state current	I_{DRM}	—	—	2.0	mA	$T_j = 150^\circ\text{C}$, V_{DRM} applied	
On-state voltage	V_{TM}	—	—	1.6	V	$T_c = 25^\circ\text{C}$, $I_{TM} = 12\text{ A}$, Instantaneous measurement	
Gate trigger voltage ^{Note2}	I	V_{FGTI}	—	—	1.5	V	$T_j = 25^\circ\text{C}$, $V_D = 6\text{ V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$
	II	V_{RGTI}	—	—	1.5	V	
	III	V_{RGTIII}	—	—	1.5	V	
Gate trigger current ^{Note2}	I	I_{FGTI}	—	—	30	mA	$T_j = 25^\circ\text{C}$, $V_D = 6\text{ V}$, $R_L = 6\ \Omega$, $R_G = 330\ \Omega$
	II	I_{RGTI}	—	—	30	mA	
	III	I_{RGTIII}	—	—	30	mA	
Gate non-trigger voltage	V_{GD}	0.2/0.1	—	—	V	$T_j = 125^\circ\text{C}/150^\circ\text{C}$, $V_D = 1/2 V_{DRM}$	
Thermal resistance	$R_{th(j-c)}$	—	—	4.3	$^\circ\text{C}/\text{W}$	Junction to case ^{Note3}	
Critical-rate of rise of off-state commutating voltage ^{Note4}	$(dv/dt)_c$	10/1	—	—	$\text{V}/\mu\text{s}$	$T_j = 125^\circ\text{C}/150^\circ\text{C}$	

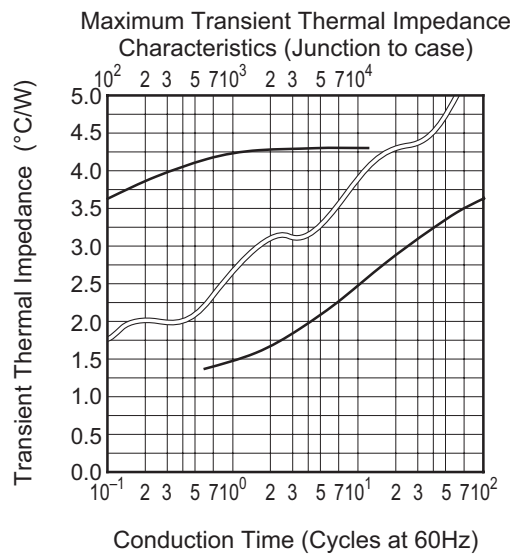
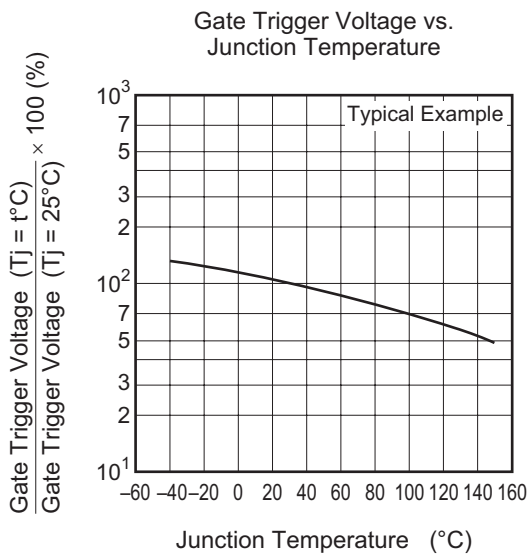
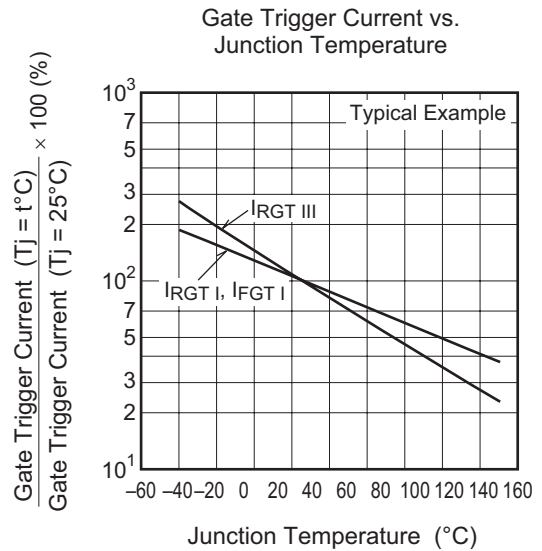
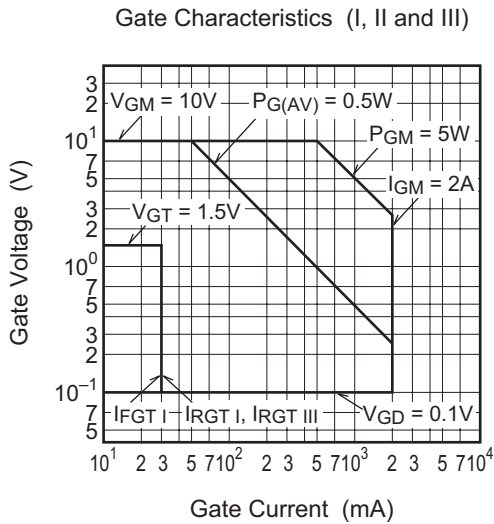
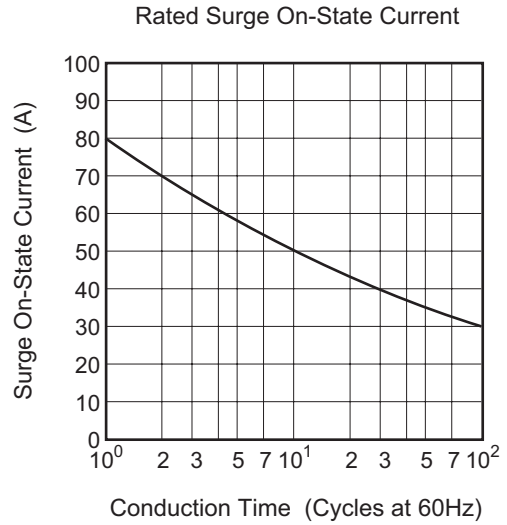
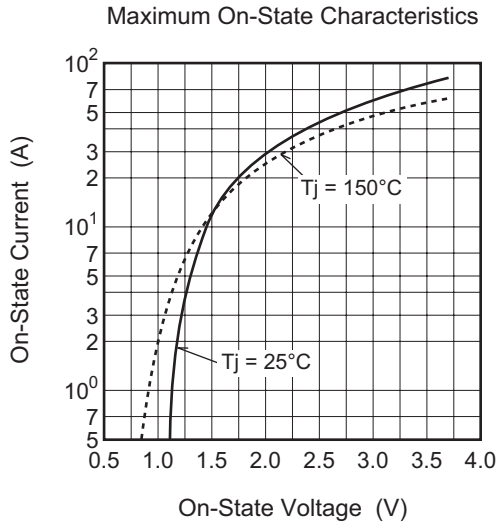
Notes: 2. Measurement using the gate trigger characteristics measurement circuit.

3. The contact thermal resistance $R_{th(c-f)}$ in case of greasing is $0.5^\circ\text{C}/\text{W}$.

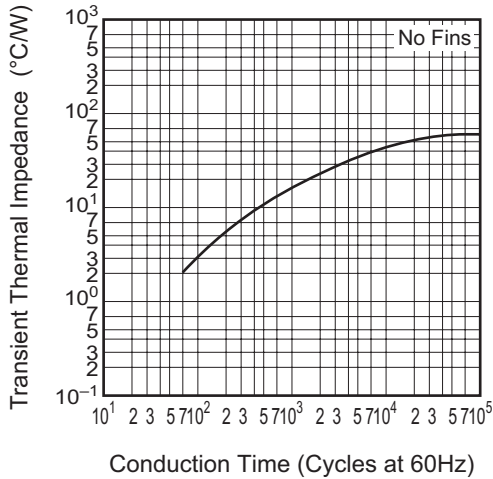
4. Test conditions of the critical-rate of rise of off-state commutating voltage is shown in the table below.

Test conditions	Commutating voltage and current waveforms (inductive load)
1. Junction temperature $T_j = 125^\circ\text{C}/150^\circ\text{C}$ 2. Rate of decay of on-state commutating current $(di/dt)_c = - 4.0\text{ A/ms}$ 3. Peak off-state voltage $V_D = 400\text{ V}$	

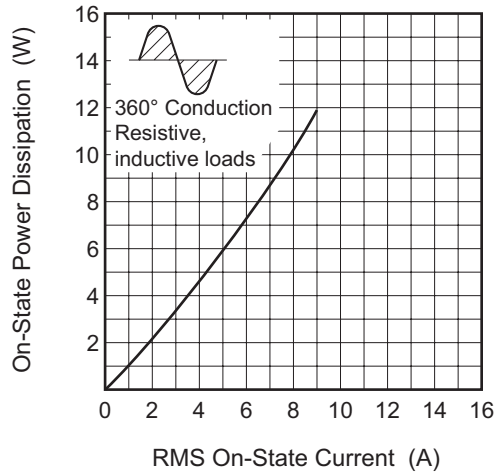
Performance Curves



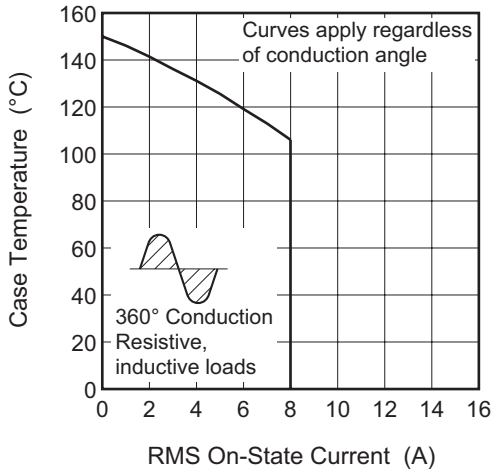
Maximum Transient Thermal Impedance Characteristics (Junction to ambient)



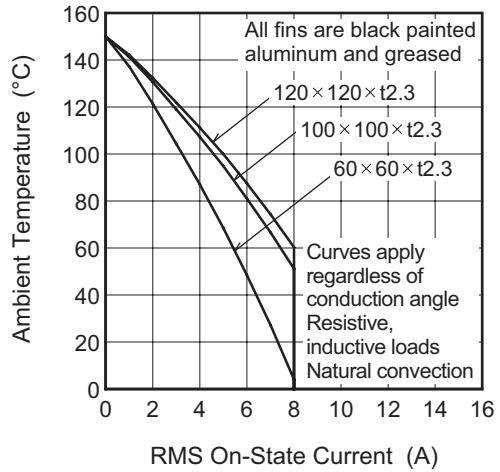
Maximum On-State Power Dissipation



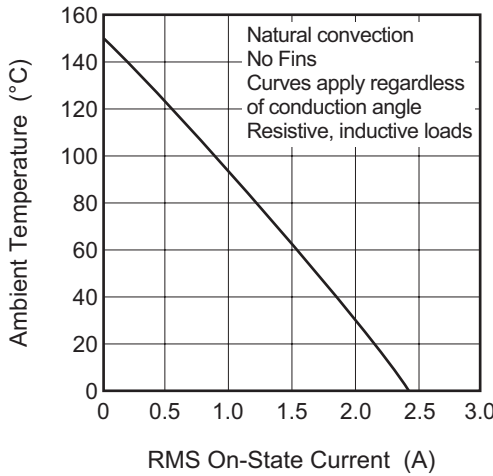
Allowable Case Temperature vs. RMS On-State Current



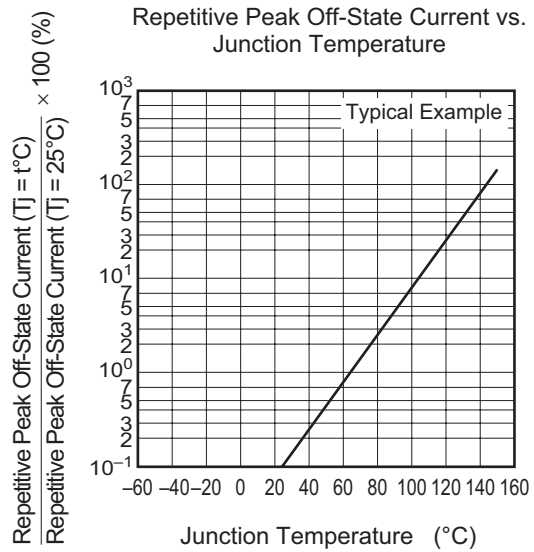
Allowable Ambient Temperature vs. RMS On-State Current



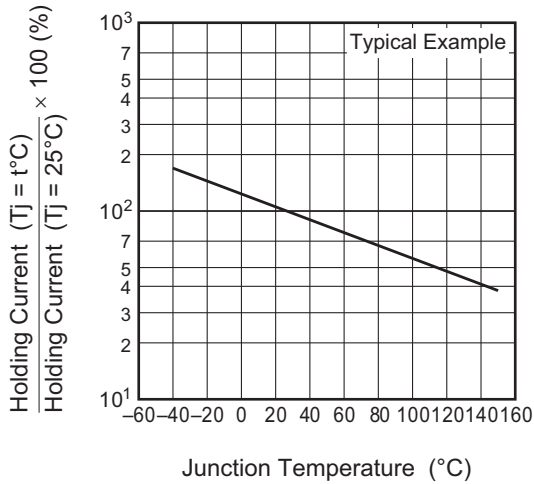
Allowable Ambient Temperature vs. RMS On-State Current



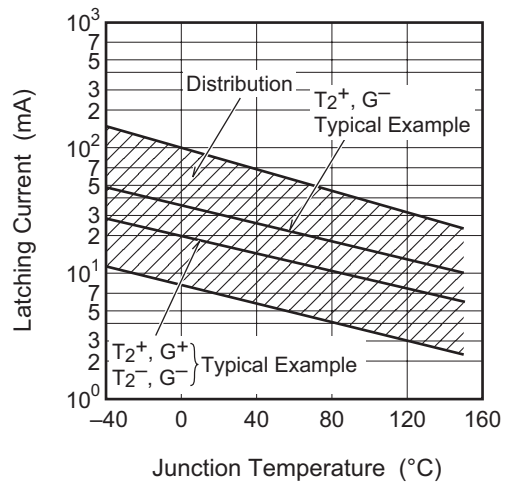
Repetitive Peak Off-State Current vs. Junction Temperature



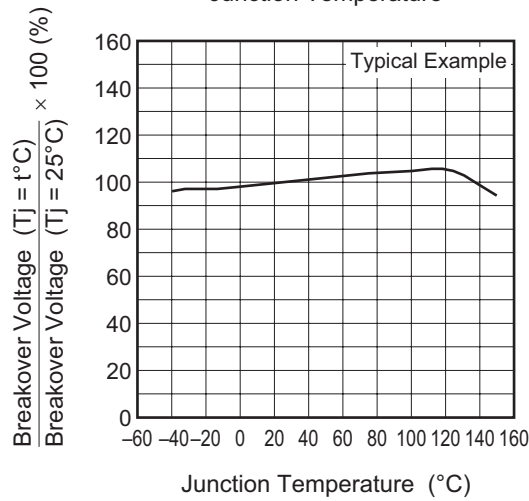
Holding Current vs. Junction Temperature



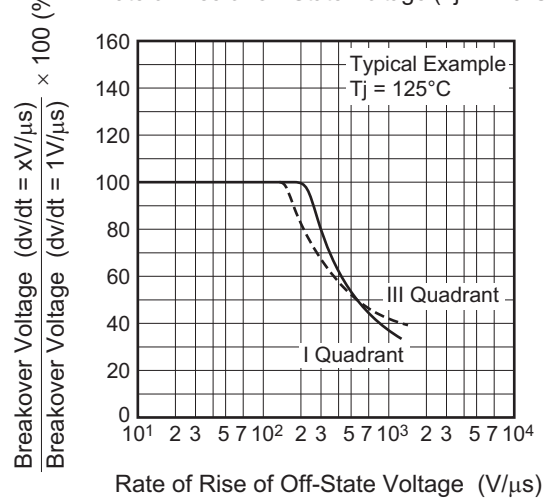
Latching Current vs. Junction Temperature



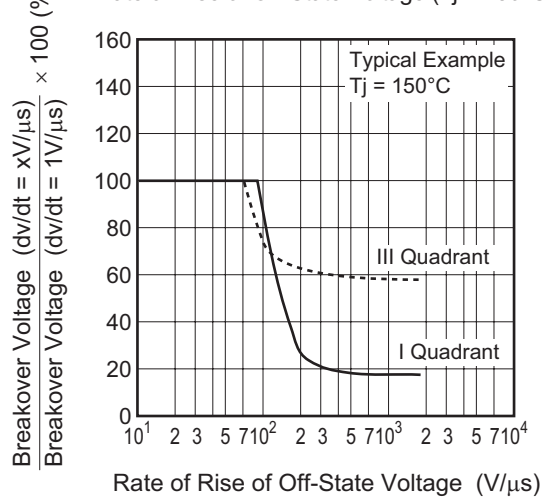
Breakover Voltage vs. Junction Temperature



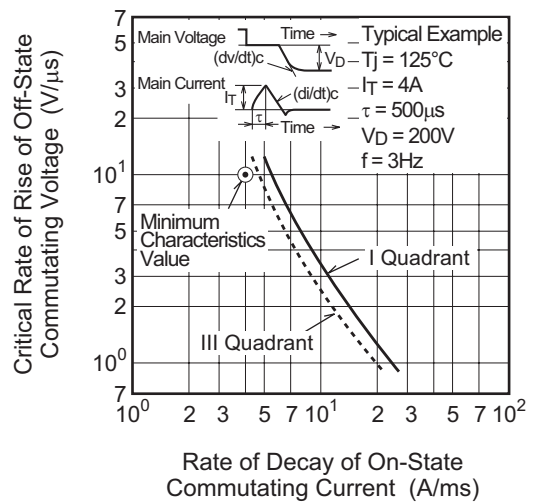
Breakover Voltage vs. Rate of Rise of Off-State Voltage (Tj = 125°C)



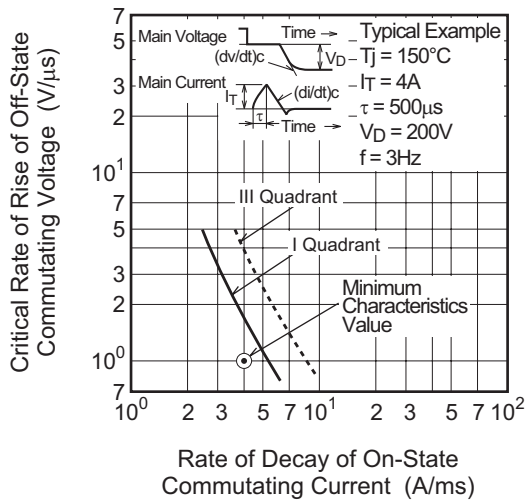
Breakover Voltage vs. Rate of Rise of Off-State Voltage (Tj = 150°C)



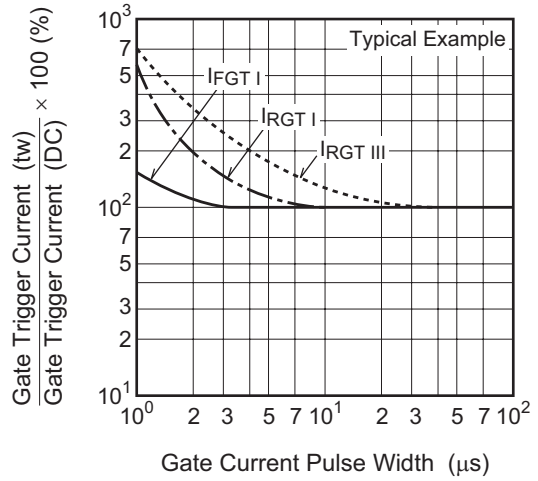
Commutation Characteristics (Tj = 125°C)



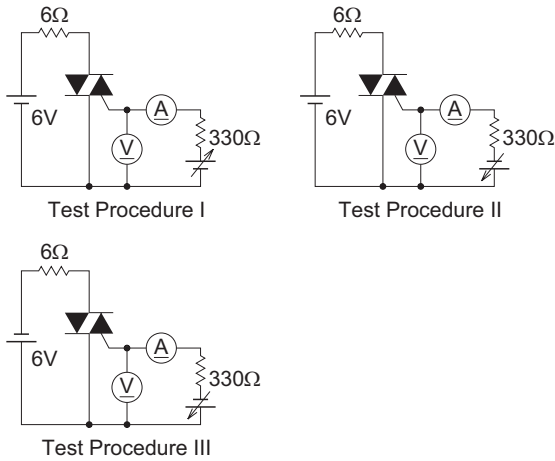
Commutation Characteristics (Tj = 150°C)



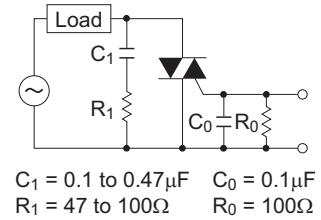
Gate Trigger Current vs. Gate Current Pulse Width



Gate Trigger Characteristics Test Circuits



Recommended Circuit Values Around The Triac



Package Dimensions

Package Name	JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
TO-220F	SC-67	PRSS0003AA-A	—	2.0g

Unit: mm

The technical drawing illustrates the BCR8PM-16LG package dimensions. The top view shows a rectangular body with a width of 10.5Max and a diameter of $\phi 3.2 \pm 0.2$. The height of the body is 17 mm. The distance from the top edge to the center of the hole is 5.0 mm. The distance from the center of the hole to the bottom edge of the body is 8.5 mm. The distance from the top edge to the start of the leads is 3.6 mm. The distance between the two leads is 2.54 mm. The length of the leads is 13.5Min. The distance from the center of the hole to the edge of the lead is 5.2 mm. The distance from the center of the hole to the edge of the lead is 1.2 mm. The distance from the center of the hole to the edge of the lead is 1.3Max. The distance from the center of the hole to the edge of the lead is 0.8 mm. The distance from the center of the hole to the edge of the lead is 2.8 mm. The distance from the center of the hole to the edge of the lead is 0.5 mm. The distance from the center of the hole to the edge of the lead is 2.6 mm. The distance from the center of the hole to the edge of the lead is 4.5 mm.

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Straight type	Vinyl sack	100	Type name	BCR8PM-16LG
Lead form	Plastic Magazine (Tube)	50	Type name – Lead forming code	BCR8PM-16LG-A8

Note : Please confirm the specification about the shipping in detail.

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Renesas Technology America, Inc.
450 Holger Way, San Jose, CA 95134-1368, U.S.A
Tel: <1> (408) 382-7500, Fax: <1> (408) 382-7501

Renesas Technology Europe Limited
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, U.K.
Tel: <44> (1628) 585-100, Fax: <44> (1628) 585-900

Renesas Technology (Shanghai) Co., Ltd.
Unit 204, 205, AZIACenter, No.1233 Lujiazui Ring Rd, Pudong District, Shanghai, China 200120
Tel: <86> (21) 5877-1818, Fax: <86> (21) 6887-7898

Renesas Technology Hong Kong Ltd.
7th Floor, North Tower, World Finance Centre, Harbour City, 1 Canton Road, Tsimshatsui, Kowloon, Hong Kong
Tel: <852> 2265-6688, Fax: <852> 2730-6071

Renesas Technology Taiwan Co., Ltd.
10th Floor, No.99, Fushing North Road, Taipei, Taiwan
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

Renesas Technology Singapore Pte. Ltd.
1 Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632
Tel: <65> 6213-0200, Fax: <65> 6278-8001

Renesas Technology Korea Co., Ltd.
Kukje Center Bldg. 18th Fl., 191, 2-ka, Hangang-ro, Yongsan-ku, Seoul 140-702, Korea
Tel: <82> (2) 796-3115, Fax: <82> (2) 796-2145

Renesas Technology Malaysia Sdn. Bhd
Unit 906, Block B, Menara Amcorp, Amcorp Trade Centre, No.18, Jalan Persiaran Barat, 46050 Petaling Jaya, Selangor Darul Ehsan, Malaysia
Tel: <603> 7955-9390, Fax: <603> 7955-9510